

AGENDA
Soldering Technology Committee
April 17, 2007 – 1:30PM

1) Introductions and Roster modifications

2) April meeting minutes approval

2 Old business

3 New business

3.1 Revision to IPC/EIA J-STD-002B

3.1.1 J-STD-002C Status

J-STD-002C will require a rebalot to include inputs from JEDEC. The committee will review the rebalot copy and discuss inputs from JEDEC.

3.2 Possible replacements for steam pre-conditioning

Committee members have agreed that an area for future work is the replacement of steam pre-conditioning. Investigation of industry data and other pre-condition methods in use will be needed. A DOE has been designed. The DOE was reviewed at the recent IPC 5-23a/b committee meeting in Los Angeles. The STC will review the DOE layout and discuss status of the sample builds.

3.3 Gauge R&R for wetting balance test

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. Team needs to discuss plans/timing for future work.

4 Next meeting

5 Adjournment

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